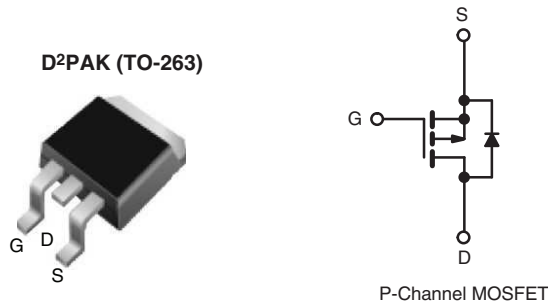


Power MOSFET

| PRODUCT SUMMARY | | |
|---------------------------|-------------------|------|
| V_{DS} (V) | - 100 | |
| $R_{DS(on)}$ (Ω) | $V_{GS} = - 10$ V | 0.20 |
| Q_g (Max.) (nC) | 61 | |
| Q_{gs} (nC) | 14 | |
| Q_{gd} (nC) | 29 | |
| Configuration | Single | |



FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Surface Mount
- Available in Tape and Reel
- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- P-Channel
- 175 °C Operating Temperature
- Fast Switching
- Compliant to RoHS Directive 2002/95/EC



RoHS*
COMPLIANT
HALOGEN
FREE
Available

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The D²PAK (TO-263) is a surface mount power package capable of accommodating die sizes up to HEX-4. It provides the highest power capability and the lowest possible on-resistance in any existing surface mount package. The D²PAK (TO-263) is suitable for high current applications because of its low internal connection resistance and can dissipate up to 2.0 W in a typical surface mount application.

| ORDERING INFORMATION | | |
|---------------------------------|-----------------------------|-------------------------------|
| Package | D ² PAK (TO-263) | D ² PAK (TO-263) |
| Lead (Pb)-free and Halogen-free | SiHF9540S-GE3 | SiHF9540STRL-GE3 ^a |
| Lead (Pb)-free | IRF9540SPbF | IRF9540STRLPbF ^a |
| | SiHF9540S-E3 | SiHF9540STL-E3 ^a |

Note

- a. See device orientation.

| ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted) | | | | |
|---|--------------------|----------------|------------------|------|
| PARAMETER | SYMBOL | LIMIT | UNIT | |
| Drain-Source Voltage | V_{DS} | - 100 | V | |
| Gate-Source Voltage | V_{GS} | ± 20 | | |
| Continuous Drain Current | V_{GS} at - 10 V | $T_C = 25$ °C | - 19 | A |
| | | $T_C = 100$ °C | - 13 | |
| Pulsed Drain Current ^a | | | - 72 | W/°C |
| Linear Derating Factor | | | 1.0 | |
| Linear Derating Factor (PCB Mount) ^e | | | 0.025 | |
| Single Pulse Avalanche Energy ^b | | E_{AS} | 640 | mJ |
| Repetitive Avalanche Current ^a | | I_{AR} | - 19 | A |
| Repetitive Avalanche Energy ^a | | E_{AR} | 15 | mJ |
| Maximum Power Dissipation | $T_C = 25$ °C | P_D | 150 | W |
| Maximum Power Dissipation (PCB Mount) ^e | | | 3.7 | |
| Peak Diode Recovery dV/dt ^c | | dV/dt | - 5.5 | V/ns |
| Operating Junction and Storage Temperature Range | | T_J, T_{stg} | - 55 to + 175 | °C |
| Soldering Recommendations (Peak Temperature) | for 10 s | | 300 ^d | |

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = - 25$ V, starting $T_J = 25$ °C, $L = 2.7$ mH, $R_g = 25$ Ω , $I_{AS} = - 19$ A (see fig. 12).
- $I_{SD} \leq - 19$ A, $dI/dt \leq 200$ A/ μ s, $V_{DD} \leq V_{DS}$, $T_J \leq 175$ °C.
- 1.6 mm from case.
- When mounted on 1" square PCB (FR-4 or G-10 material)

* Pb containing terminations are not RoHS compliant, exemptions may apply

| THERMAL RESISTANCE RATINGS | | | | | | |
|--|-------------------|------|------|------|------|--|
| PARAMETER | SYMBOL | MIN. | TYP. | MAX. | UNIT | |
| Maximum Junction-to-Ambient (PCB Mount) ^a | R _{thJA} | - | - | 40 | °C/W | |
| Maximum Junction-to-Case (Drain) | R _{thJC} | - | - | 1.0 | | |

Note

a. When mounted on 1" square PCB (FR-4 or G-10 material).

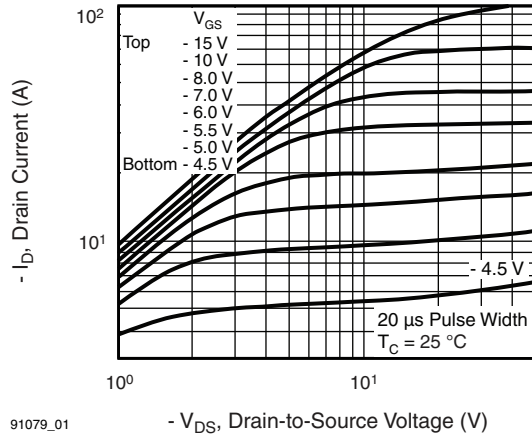
| SPECIFICATIONS (T _J = 25 °C, unless otherwise noted) | | | | | | | |
|---|----------------------------------|--|--|-------|---------|-------|------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | V _{GS} = 0 V, I _D = - 250 μA | | - 100 | - | - | V |
| V _{DS} Temperature Coefficient | ΔV _{DS} /T _J | Reference to 25 °C, I _D = - 1 mA | | - | - 0.087 | - | V/°C |
| Gate-Source Threshold Voltage | V _{GS(th)} | V _{DS} = V _{GS} , I _D = - 250 μA | | - 2.0 | - | - 4.0 | V |
| Gate-Source Leakage | I _{GSS} | V _{GS} = ± 20 V | | - | - | ± 100 | nA |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = - 100 V, V _{GS} = 0 V | | - | - | - 100 | μA |
| | | V _{DS} = - 80 V, V _{GS} = 0 V, T _J = 150 °C | | - | - | - 500 | |
| Drain-Source On-State Resistance | R _{DS(on)} | V _{GS} = - 10 V | I _D = - 11 A ^b | - | - | 0.20 | Ω |
| Forward Transconductance | g _{fs} | V _{DS} = - 50 V, I _D = - 11 A | | 6.2 | - | - | S |
| Dynamic | | | | | | | |
| Input Capacitance | C _{iss} | V _{GS} = 0 V, V _{DS} = - 25 V, f = 1.0 MHz, see fig. 5 | | - | 1400 | - | pF |
| Output Capacitance | C _{oss} | | | - | 590 | - | |
| Reverse Transfer Capacitance | C _{rss} | | | - | 140 | - | |
| Total Gate Charge | Q _g | V _{GS} = - 10 V | I _D = - 19 A, V _{DS} = - 80 V, see fig. 6 and 13 ^b | - | - | 61 | nC |
| Gate-Source Charge | Q _{gs} | | | - | - | 14 | |
| Gate-Drain Charge | Q _{gd} | | | - | - | 29 | |
| Turn-On Delay Time | t _{d(on)} | V _{DD} = - 50 V, I _D = - 19 A, R _G = 9.1 Ω, R _D = 2.4 Ω, see fig. 10 ^b | | - | 16 | - | ns |
| Rise Time | t _r | | | - | 73 | - | |
| Turn-Off Delay Time | t _{d(off)} | | | - | 34 | - | |
| Fall Time | t _f | | | - | 57 | - | |
| Internal Drain Inductance | L _D | Between lead, 6 mm (0.25") from package and center of die contact | | - | 4.5 | - | nH |
| Internal Source Inductance | L _S | | | - | 7.5 | - | |
| Drain-Source Body Diode Characteristics | | | | | | | |
| Continuous Source-Drain Diode Current | I _S | MOSFET symbol showing the integral reverse p - n junction diode | | - | - | - 19 | A |
| Pulsed Diode Forward Current ^a | I _{SM} | | | - | - | - 72 | |
| Body Diode Voltage | V _{SD} | T _J = 25 °C, I _S = - 19 A, V _{GS} = 0 V ^b | | - | - | - 5.0 | V |
| Body Diode Reverse Recovery Time | t _{rr} | T _J = 25 °C, I _F = - 19 A, di/dt = 100 A/μs ^b | | - | 130 | 260 | ns |
| Body Diode Reverse Recovery Charge | Q _{rr} | | | - | 0.35 | 0.70 | nC |
| Forward Turn-On Time | t _{on} | Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L _D) | | | | | |

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).

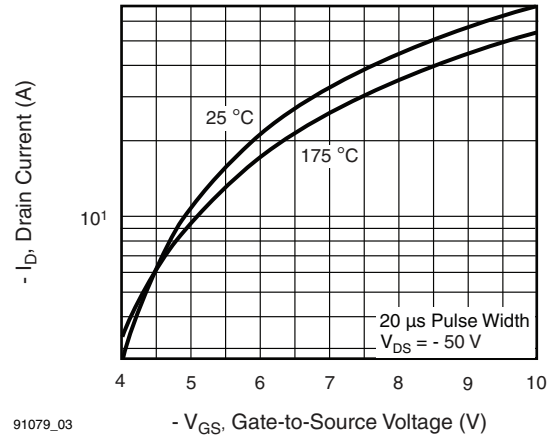
b. Pulse width ≤ 300 μs; duty cycle ≤ 2 %.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



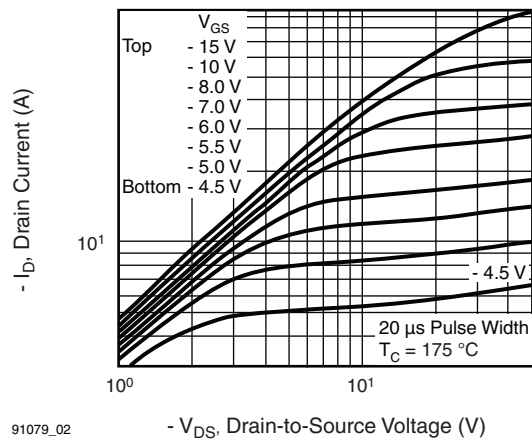
91079_01

Fig. 1 - Typical Output Characteristics, $T_C = 25\text{ }^\circ\text{C}$



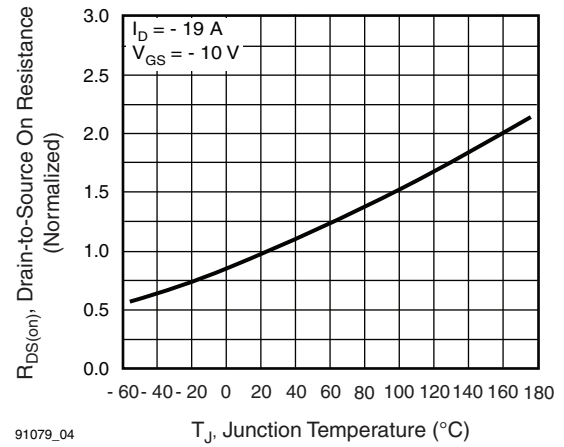
91079_03

Fig. 3 - Typical Transfer Characteristics



91079_02

Fig. 2 - Typical Output Characteristics, $T_C = 175\text{ }^\circ\text{C}$



91079_04

Fig. 4 - Normalized On-Resistance vs. Temperature

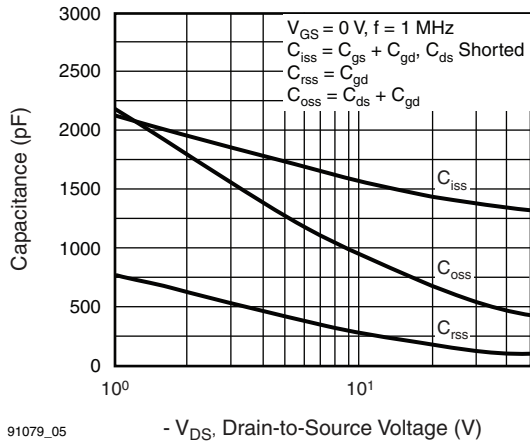


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

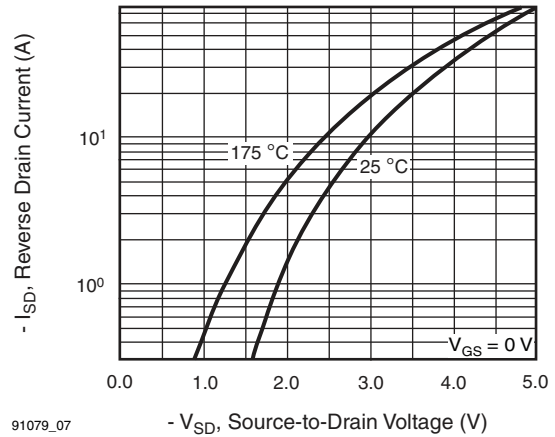


Fig. 7 - Typical Source-Drain Diode Forward Voltage

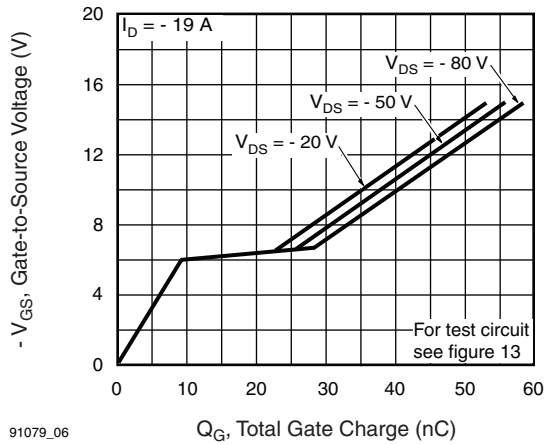


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

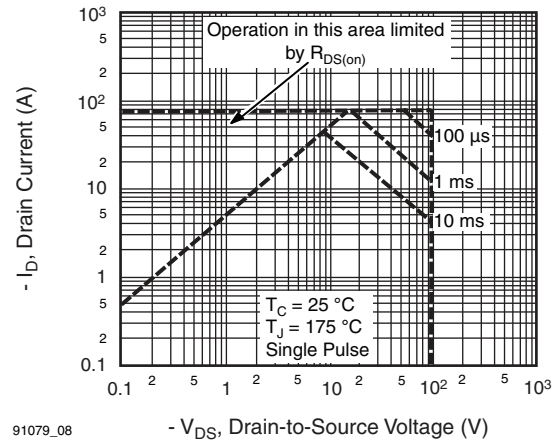


Fig. 8 - Maximum Safe Operating Area

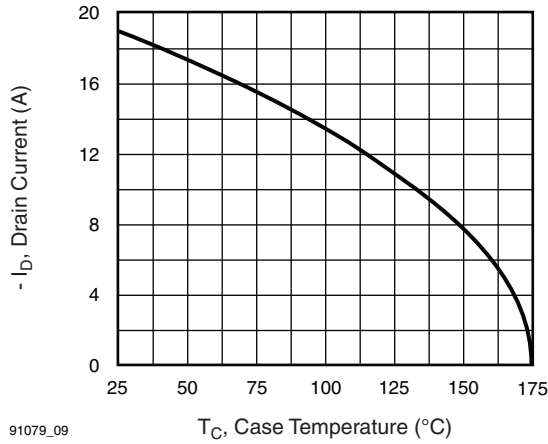


Fig. 9 - Maximum Drain Current vs. Case Temperature

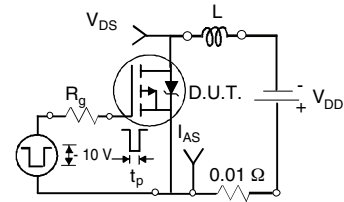


Fig. 10a - Switching Time Test Circuit

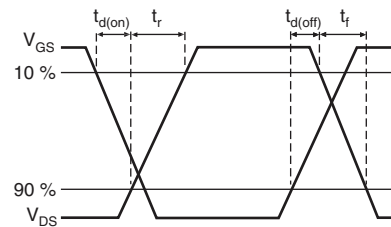


Fig. 10b - Switching Time Waveforms

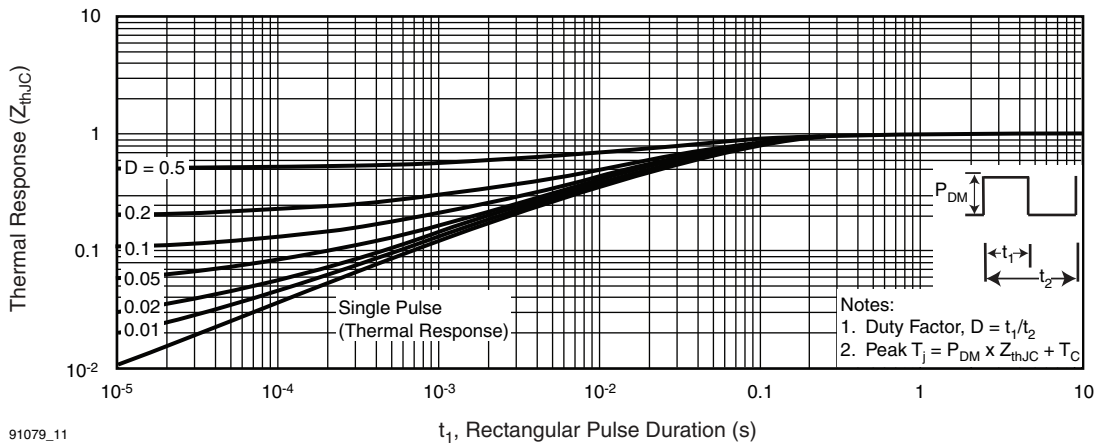


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

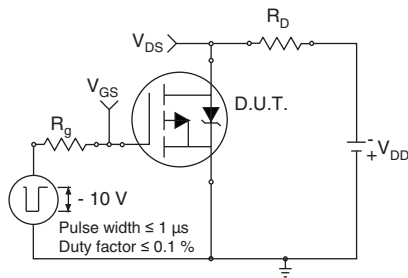


Fig. 12a - Unclamped Inductive Test Circuit

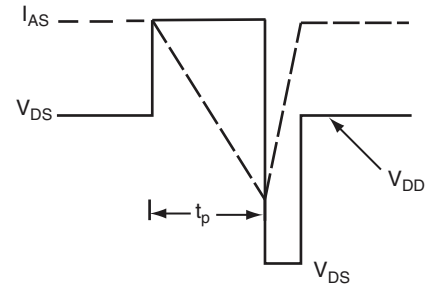
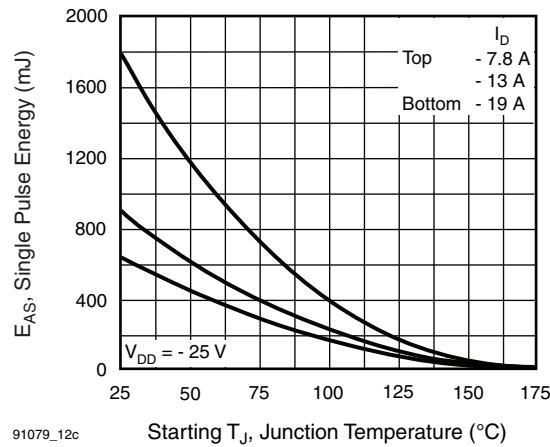


Fig. 12b - Unclamped Inductive Waveforms



91079_12c

Fig. 12c - Maximum Avalanche Energy vs. Drain Current

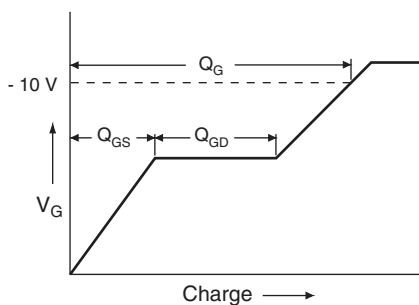


Fig. 13a - Basic Gate Charge Waveform

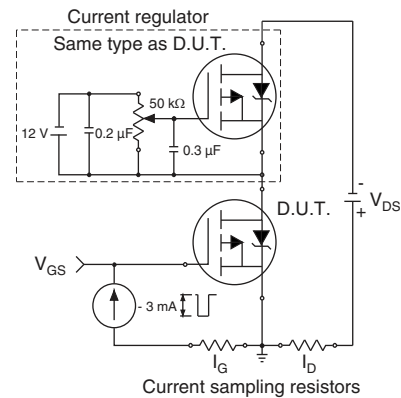
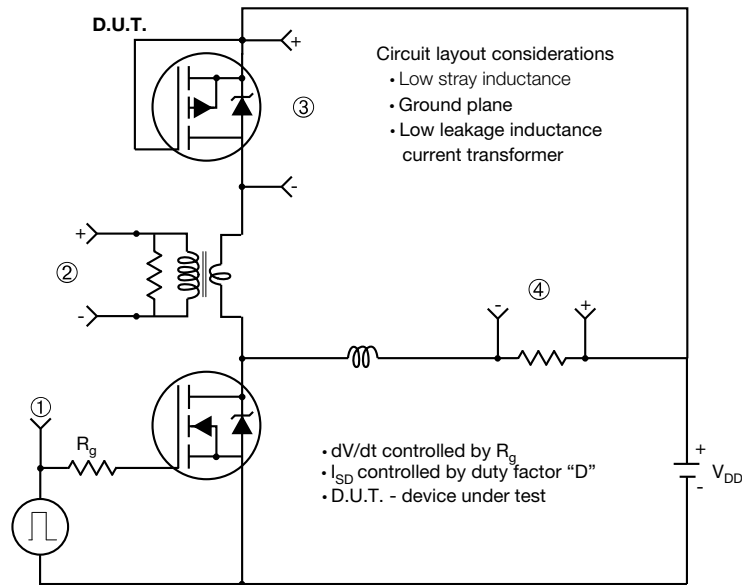
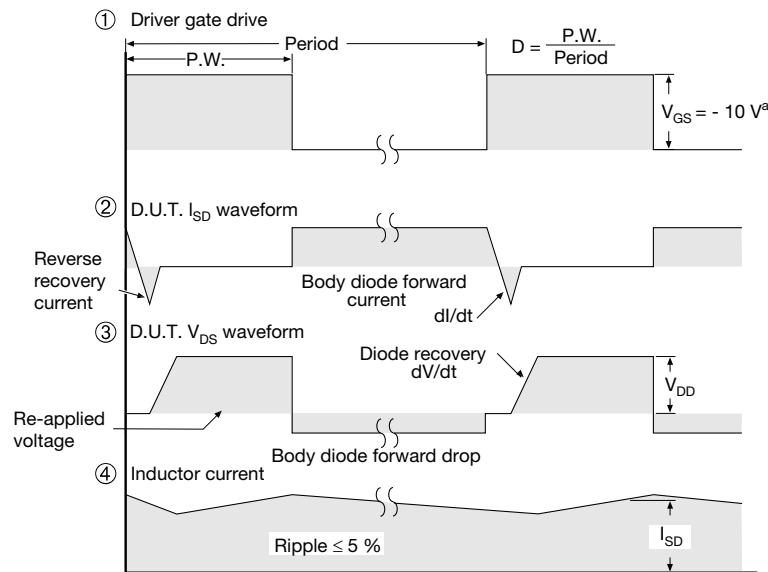


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



Note
 • Compliment N-Channel of D.U.T. for driver

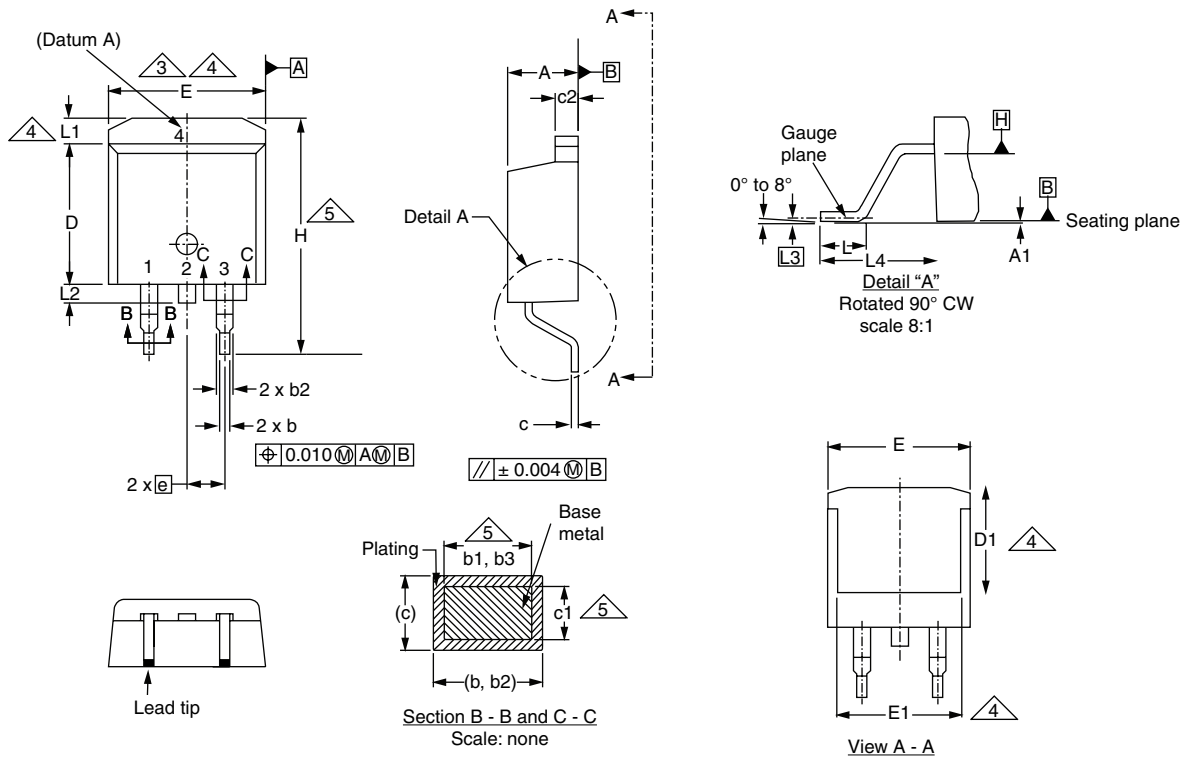


Note
 a. $V_{GS} = -5\text{ V}$ for logic level and -3 V drive devices

Fig. 14 - For P-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?91079.

TO-263AB (HIGH VOLTAGE)



| DIM. | MILLIMETERS | | INCHES | |
|------|-------------|------|--------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| A | 4.06 | 4.83 | 0.160 | 0.190 |
| A1 | 0.00 | 0.25 | 0.000 | 0.010 |
| b | 0.51 | 0.99 | 0.020 | 0.039 |
| b1 | 0.51 | 0.89 | 0.020 | 0.035 |
| b2 | 1.14 | 1.78 | 0.045 | 0.070 |
| b3 | 1.14 | 1.73 | 0.045 | 0.068 |
| c | 0.38 | 0.74 | 0.015 | 0.029 |
| c1 | 0.38 | 0.58 | 0.015 | 0.023 |
| c2 | 1.14 | 1.65 | 0.045 | 0.065 |
| D | 8.38 | 9.65 | 0.330 | 0.380 |

| DIM. | MILLIMETERS | | INCHES | |
|------|-------------|-------|-----------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| D1 | 6.86 | - | 0.270 | - |
| E | 9.65 | 10.67 | 0.380 | 0.420 |
| E1 | 6.22 | - | 0.245 | - |
| e | 2.54 BSC | | 0.100 BSC | |
| H | 14.61 | 15.88 | 0.575 | 0.625 |
| L | 1.78 | 2.79 | 0.070 | 0.110 |
| L1 | - | 1.65 | - | 0.066 |
| L2 | - | 1.78 | - | 0.070 |
| L3 | 0.25 BSC | | 0.010 BSC | |
| L4 | 4.78 | 5.28 | 0.188 | 0.208 |

ECN: S-82110-Rev. A, 15-Sep-08
DWG: 5970

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimensions are shown in millimeters (inches).
3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
5. Dimension b1 and c1 apply to base metal only.
6. Datum A and B to be determined at datum plane H.
7. Outline conforms to JEDEC outline to TO-263AB.



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